

# 3A, 100V - 200V Ultra Fast Surface Mount Rectifier

#### **FEATURES**

- AEC-Q101 qualified
- Planar technology
- · Low power loss, high efficiency
- Ideal for automated placement
- Wettable flank
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

### **APPLICATIONS**

- High frequency switching
- DC/DC
- Snubber

### **MECHANICAL DATA**

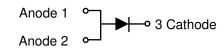
- Case: TO-277A (SMPC4.6U)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.102g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	3	Α	
$V_{RRM}$	100 - 200	V	
I <sub>FSM</sub>	85	Α	
T <sub>J MAX</sub>	175	°C	
Package	TO-277A (SMPC4.6U)		
Configuration	Single die		





TO-277A (SMPC4.6U)



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER		SYMBOL	PUUP3BH	PUUP3DH	UNIT
Marking code on the device			PU3BH	PU3DH	
Repetitive peak reverse voltage		V <sub>RRM</sub>	100	200	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	70	140	V
Forward current		l <sub>F</sub>	3		Α
Surge peak forward current single half	t = 8.3ms	. 85		35	A
sine-wave superimposed on rated load	t = 1.0ms	I <sub>FSM</sub>	190		
Junction temperature		TJ	-55 to +175		°C
Storage temperature		T <sub>STG</sub>	-55 to +175		°C



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance <sup>(1)</sup>	R <sub>eJL</sub>	2.0	°C/W	
Junction-to-ambient thermal resistance <sup>(2)</sup>	R <sub>eJA</sub>	52.4	°C/W	
Junction-to-case thermal resistance <sup>(2)</sup>	R <sub>eJC</sub>	11.4	°C/W	

## **Thermal Performance Notes:**

- 1. With ideal heat sink
- 2. Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	R CONDITIONS		TYP	MAX	UNIT
	I <sub>F</sub> = 1.5A, T <sub>J</sub> = 25°C		0.81	-	V
Forward voltage <sup>(1)</sup>	$I_F = 3.0A, T_J = 25^{\circ}C$	W	0.86	0.93	V
	I <sub>F</sub> = 1.5A, T <sub>J</sub> = 125°C	V <sub>F</sub>	0.66	-	V
	I <sub>F</sub> = 3.0A, T <sub>J</sub> = 125°C		0.73	-	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	T <sub>J</sub> = 25°C		-	2	μΑ
	T <sub>J</sub> = 125°C	l <sub>R</sub>	-	10	μΑ
Junction capacitance	1MHz, V <sub>R</sub> = 4.0V	CJ	47	-	pF
Doverse receivery time	$I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$	+	-	25	ns
Reverse recovery time	$I_F = 1.0A$ , $di/dt = 50A/\mu s$ , $V_R = 30V$	t <sub>rr</sub>	31	-	
Reverse recovery current		I <sub>RM</sub>	4.9	-	Α
Reverse recovery charge	$I_F = 3.0A$ , di/dt = 200A/ $\mu$ s, $V_R = 100V$	Q <sub>rr</sub>	51	-	nC
Reverse recovery time		t <sub>rr</sub>	23	-	ns

### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION		
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING
PUUP3xH	TO-277A (SMPC4.6U)	6,000/ Tape & Reel

## Notes:

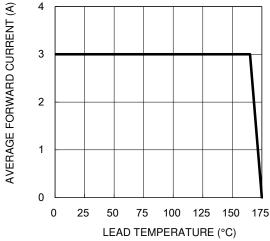
1. "x" defines voltage from 100V(PUUP3BH) to 200V(PUUP3DH)

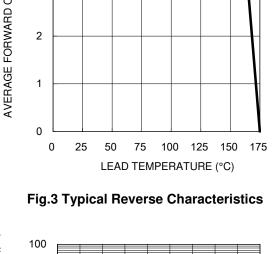


## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.1 Forward Current Derating Curve







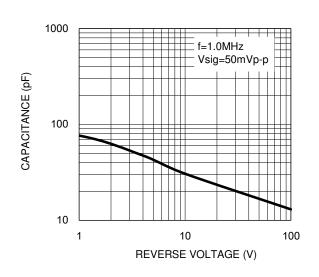
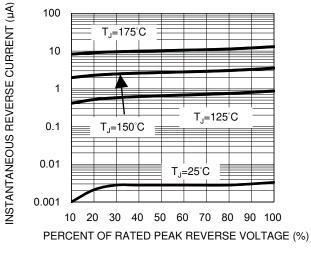


Fig.4 Typical Forward Characteristics



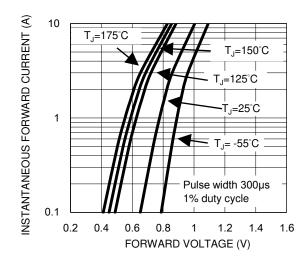
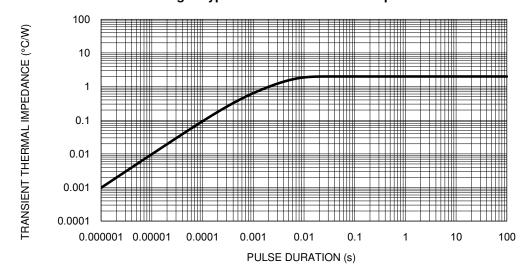


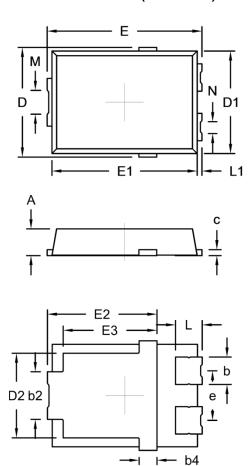
Fig.5 Typical Transient Thermal Impedance





# **PACKAGE OUTLINE DIMENSIONS**

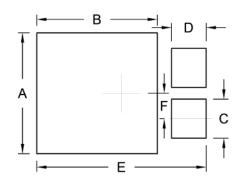
# TO-277A (SMPC4.6U)



DIM.	Unit (mm)		Unit (	inch)
DIIVI.	Min.	Max.	Min.	Max.
А	1.00	1.20	0.039	0.047
b	1.05	1.35	0.041	0.053
b2	1.90	2.20	0.075	0.087
b4	0.75 (	NOM.)	0.030	(NOM.)
С	0.15	0.40	0.006	0.016
D	4.45	4.75	0.175	0.187
D1	4.25	4.35	0.167	0.171
D2	3.40	3.70	0.134	0.146
E	6.35	6.65	0.250	0.262
E1	6.05	6.15	0.238	0.242
E2	4.40	4.80	0.173	0.189
E3	3.94 (NOM.)		0.155	(NOM.)
е	2.08 (NOM.)		0.082	(NOM.)
L	0.94	1.24	0.037	0.049
L1	0.05	0.35	0.002	0.014
М	0.65	1.15	0.026	0.045
N	0.25	0.75	0.010	0.030

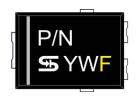
Package body size D1 and E1 do not include mold flash Mold flash shall not exceed 0.1mm per side

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	4.95	0.195
В	4.95	0.195
С	1.60	0.063
D	1.42	0.056
E	6.95	0.274
F	1.04	0.041

# **MARKING DIAGRAM**



P/N = Marking Code YW = Date Code F = Factory Code



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